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Absolute Maximum Ratings (Vss=0V)

Parameter	Symbol	Rating	Unit
Logic Supply Voltage	V_{CC}	-0.3 to 7.0	Vdc
Analog Supply Voltage	V_{DD}	-.3 to 35.0	Vdc
Logic Input Voltage	V_{LIN}	-.3 to $V_{CC}+.3$	Vdc
Storage Temperature	T_{STG}	-55 to 125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Max	Units
Logic Supply Voltage	V_{CC}		3.0	5.5	Vdc
Analog Supply Voltage	V_{DD}		15	30	Vdc
GG Voltage	V_{GG}	$V_{DD} \geq 15V$	0	12	Vdc
External RGPIn Resistor	R_{RG}		-0.1%	+0.1%	10.8K Ω
High Logic Input Level	V_{IH}		$V_{CC} - 0.6$	$V_{CC} + 0.2$	Vdc
Low Logic Input Level	V_{IL}		-0.2	.6	Vdc
High Logic Level Input Current	I_{IH}		-10	10	μA
Low Logic Level Input Current	I_{IL}		-10	10	μA
High Logic Output Level	V_{OH}	$I_{OH} > -10\mu A$	$V_{CC} - 0.2$		V
Low Logic Output Level	V_{OL}	$I_{OL} < 10\mu A$		0.2	V
Logic Supply Current	I_{CC}			7	mA
Analog Supply Current**	I_{DD}			6.0 + Iout	mA
Operating Temperature (Junction)	T_J		20	100	°C

**Analog supply current is highly dependable on the output current of the 192 output channels (Iout), which is determined by the application.

Note: V_{dout} , I_{bank} , and I_{die} are transferred to the output parameters channels table.

Digital Timing for Vcc in Range of 4.5 to 5.5 VDC

Parameter	Symbol	Min	Typ	Max	Units
Shift Clock Frequency ($V_{CC}=4.5 + 5.5V$)	f_{CLK}			55	MHz
Shift Clock Frequency ($V_{CC}=3.0$ to $4.4V$)				40	MHz
Shift Clock Frequency Pulse Width ($V_{CC}=4.5 + 5.5V$)	t_{SPW}	7	22		nS
Shift Clock Frequency Pulse Width ($V_{CC}=3.0$ to $4.4V$)	t_{SPW}	9.6	30		nS
Shift Clock Frequency Duty Cycle	DC_{SCK}	40	50	60	%
Shift Clock to Latch Delay	t_{DSKL}	3 (clock Cycles)			nS
Exposure Clock Frequency	f_{EKF}			10	MHz
Exposure Clock Pulse Width	t_{EPW}		40	500	nS
Exposure Duty Cycle	DC_{EX}	40	50	60	%
Data Setup Time	t_{DSU}	5	—	—	nS
Data Hold Time	t_{DHD}	5	—	—	nS
Token Setup Time	t_{TSU}	5	—	—	nS
Token Hold Time	t_{THD}	5	—	—	nS
Token Bit Output Delay	t_{STD}	—	—	13	nS
Token Bit Pulse Width	t_{TPW}	15	—	—	nS
Latch Pulse Width	t_{LAPW}	50	—	—	nS
Last data to Latch Enable Time	t_{DLD}	200	—	—	nS
Latch Disable to Exposure Clock Time	t_{LED}	50	—	—	nS
Exposure Clock to Latch Enable Time	t_{DLE}	50	—	—	nS
Standby to Ready Time	t_{STBY}			10	mS

Output Channel Parameters

Parameter	Symbol	Typ	Min	Max	Units
Driver Output Voltage Compliance	V_{Qn}			$V_{DD}-3$	Vdc
Per bank max to min channel output current ratio	I_{BANK}	$0 < V_{Qn} < V_{DD} - 3$, V_{Qn} match to 2V	1.0	1.04	A/A
High output die to low output die average output current ratio	I_{DIE}	$0 < V_{Qn} < V_{DD} - 3$, V_{Qn} match to 2V R_{RG} match to 0.1%	1.0	1.02	A/A
Output Current Rise Time	t_{IOR}	—	—	200	nS
Output Current Fall Time	t_{IOF}	—	—	200	nS
Output Current Settling Time	t_{IOS}	—	—	350	nS
Exposure Clock to Output High Delay	t_{OHD}	—	—	220	nS
Exposure Clock to Output Low Delay	t_{OLD}	—	—	220	nS
Channel output current rise/fall time	t_{IORE}	10% to 90%		250	nS
Shorting Switch Resistance		$V(Qn) = IV$		800	Ω

Signal Definition

Name	I/O/A	Description
V _{DD}		Power supply for the 192 current driver output channels - 6 pads
V _{CC}		Low voltage logic power supply - 2 pads
GND		Ground - 4 pads
ISHRT		Ground used to short the 192 current driver output channels - 4 pads. Note: There can be high currents on this line. It should be separated from the circuit ground pads (GND) to prevent ground bounce.
RSTB	I	Reset: Active low signal used to reset digital logic for test purposes. This input is pulled high internally.
CLKSH	I	Token Shift Clock: Used to shift tokens down the length of the driver IC. The direction of token shift is determined by DIRTKN pin. It is possible to load only a portion of the 192 output channels prior to latching in applications not requiring the full 192 channels. The speed of the clock is from DC to 55 MHz at 5V logic power supply (40 MHz at 3.3V).
LTKNB	I/O	Left Token Bit: Used to pass the tokens into and out of the driver IC. The pin is used as input for shift right and as output for shift left. High state represents the presence of token. The shifting is performed from DC to 55 MHz (40 MHz at 3.3V).
RTKNB	I/O	Right Token Bit: Used to pass the tokens into and out of the driver IC. The pin is used as input for shift left and as output for shift right. High state represents the presence of token. The shifting is performed from DC to 55 MHz (40 MHz at 3.3V).
DIRTKN	I	Token Direction: Used to determine the shift direction of the token. When the signal is high, causes the token to shift left to right (1→64) and when the signal is low causes the token to shift to left (64→1). This input is pulled high internally. The token shifts 3 cells at a time to account for the 3 parallel data inputs.
LE	I	Latch Enable: Active high signal used to latch RGB data from the driver outputs into a set of transfer latches. Once a line of data is latched into the transfer latch, OLED exposure can begin. At the same time, a new line of exposure data can be loaded into the input register of the driver IC. On the rising edge of the of LE, all token registers are cleared, the exposure counter is asynchronously preset to a low state and exposure data is allowed to pass from the input register to the transfer latch. On the falling edge of LE, the exposure counter and output drivers are enabled within t _{LED} (50 ns).
DA(5-0)	I	6-bit Data input A. Signal bus used for the exposure data input word for outputs 1,4,7,...,190. The driver performs at clock speed from DC to 55 MHz (40 MHz at 3.3V).
DB(5-0)	I	6-bit Data input B. Signal bus used for the exposure data input word for outputs 2,5,8,...,191. The driver performs at clock speed from DC to 55 MHz (40 MHz at 3.3V).
DC(5-0)	I	6-bit Data input C. Signal bus used for the exposure data input word for channels 3,6,9,...,192. The driver performs at clock speed from DC to 55 MHz (40 MHz at 3.3V).
CLKEX	I	Exposure Clock: Signal (DC to 10 MHz signal) used to clock the input of the driver ICs exposure counter (6-bits). The signal is used to cycle the driver IC internal counter from 0 up to 63. The signal must be cycled at least 64 times between LE pulses to completely cycle the counter. The first rising edge of CLKEX will enable all non zero outputs without changing the counter. Additional rising edges of CLKEX will increment the counter. When the counter and data of values for an output match, the output is disabled until LE re-enables the exposure counter. Cycles of CLKEX beyond 64 will have no effect until the next cycle of LE re-enables the counter.
TGR	I	Binary/Grayscale: Signal used to determine if the driver IC is either 6 bit grayscale or binary. Low → grayscale. High → Binary. This input is internally pulled to a logic low.
GG	A	Global Gain: Used to set the global current gain. The voltage range on this pin is 0V to 12V when V _{DD} is ≥ 15V. The base current level is GG/RG, with a peak base current level of 1.455mA. This input is internally pulled to a logic low.

Signal Definition (continued)

Name	I/O/A	Description
RG	A	Resistor Gain: Used to set the global current gain. A precision resistor shall be connected from this node to analog ground which, in conjunction with the GG input voltage, sets up the base current level of the chip.
GA(2-0)	I	A Gain: Used to set the current on driver output channels 1,4,7,...,190. This input is internally pulled to a logic low.
GB(2-0)	I	B Gain: Used to set the current on driver output channels 2,5,8,...,191. This input is internally pulled to a logic low.
GC(2-0)	I	C Gain: Used to set the current on driver output channels 3,6,9,...,192. This input is internally pulled to a logic low.
STBY	I	Standby Reset: Active high signal used to place the IC in a low power standby mode. When in the high state the IC is non-functional and power dissipation is minimized. This input is internally pulled to a logic low.
SDM(1-0)	I	Stripe/Diagonal/Mosaic: These input signals are used to modify the output channel current levels depending on which row of the display is active. The falling edge of LE is used to modify the A, B, C channels. When the STBY is set to a logic high, the A, B, C channel outputs are reset to their initial mapping. These inputs are internally pulled to a logic high. (See the SDM function below).
$\overline{\text{SWC}}$	I	Switch Channels: This input signal is used to control when the individual output channels are in the tri-state condition (current is not sourced and the switch to ground is off). When the $\overline{\text{SWC}}$ input is in the high state, each output channel turns the switch to ground on as soon as the data count is matched and current source disabled. When $\overline{\text{SWC}}$ is in the low state, each channel remains in the tri-state condition from when the current source is disabled until the counter equals 63. This input is internally pulled to a logic low.
TST(9-0)	I	These pins should be left open circuited.
TEST(2-0)	A	These pins should be left open circuited.
Q1-Q192	A	OLED current source driver outputs.

Note: A= > analog, I= > digital input, O= > digital output

Functional Description

Output Current Hold-On-Time Control

There are two modes for controlling the 192 outputs current hold-on-times:

- 1- Grayscale: The grayscale is obtained when the TGR pin is low or open. Each of the three banks has a 6-bit control word, DA(5-0), DB(5-0), and DC(5-0), that is updated at the CLKSH signal clock which allows each output to turn on for a period of 0 to 63 counts of the CLKEX signal clock.
- 2- Binary Mode: Binary mode is obtained when the TGR input signal is high. Data is loaded in a similar way that is described in the grayscale mode. After the data is latched the DA5, DB5, or DC5 data bit is gated with CLKEX to determine the on or off status of the output drivers.

Output Current Magnitude Control

GG, RG, GA(2-0), GB(2-0), and GC(2-0) controls the output current of the output drivers in the three banks. A precision 10.8 K Ω (+/- 0.1%) resistor is tied from RG to ground. A voltage between 0.5 and 12V is applied to GG to adjust the overall brightness of the display. GA(2-0), GB(2-0), and GC(2-0) are 3-bit logic inputs that control the relative brightness of the A, B, and C banks output drivers respectively. The total output driver current is limited to a maximum of 0.6 mA for each output. Below this limit, the individual output current for banks A, B, and C is programmed as follows:

$$I(\text{out}) = \frac{V(\text{GG})}{10.8 \text{ Kohms}} \times \frac{F(\text{gain})}{16} = 5.79\text{E-}6 * V(\text{GG}) * F(\text{gain})$$

Where:

GA/GB/GC (2-0)	F(gain)	GA/GB/GC (2-0)	F(gain)
0x7	31	0x3	16
0x6	26	0x2	14
0x5	22	0x1	12
0x4	19	0x0	10

Functional Description (continued)

Output Current Turn-Off Control

The $\overline{\text{SWC}}$ input signal controls turn-off of the driver outputs. When the $\overline{\text{SWC}}$ signal is high, each output is switched to ground when the data count is matched and simultaneously disables the current source. When $\overline{\text{SWC}}$ is low, each output remains in a tri-state condition from when the current source is disabled until the counter equals 63.

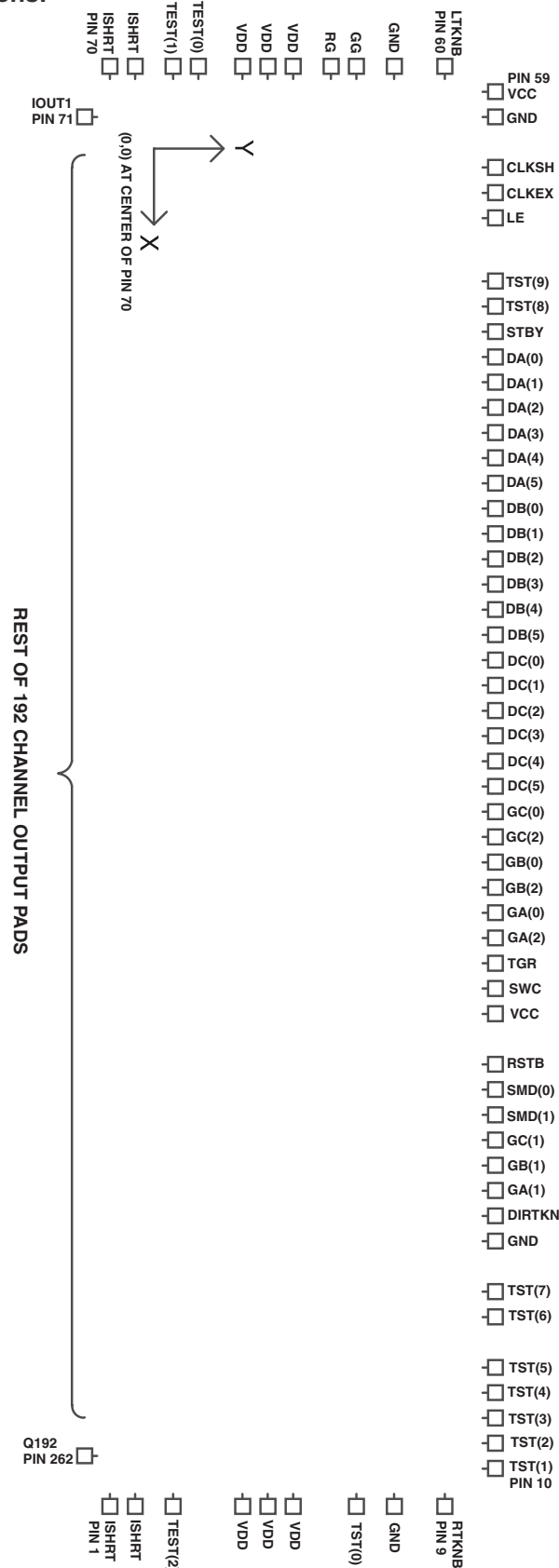
SDM Function

The SDM1 and SDM0 inputs determine how the A, B, and C display output banks are configured. They may also be used to generate special effects in the display. When the SDM signals are open or high, the MXED101 is in its normal operating mode (stripe mode). The SDM mapping to screen configuration is updated each time LE goes high and is as follows:

SDM1	SDM0	Mode	Line 1	Line 2	Line 3	Line 4	Line 5	Line 6
1	1	Stripe	ABC	ABC	ABC	ABC	ABC	ABC
1	0	Diagonal	ABC	CAB	BCA	ABC	CAB	BCA
0	1	Mosaic Intv	BCA	BCA	BCA	BCA	BCA	BCA
0	0	Mosaic	ABC	BCA	ABC	BCA	ABC	BCA

Note: there is no effect on the DA, DB, DC data buses and which banks they load. Under all SDM1, 0 conditions, DA loads banks 1,4,7,...,190, DB loads banks 2,5,8,...,191, and DC loads banks 3,6,9,...,192.

Die Size and Pad Locations:



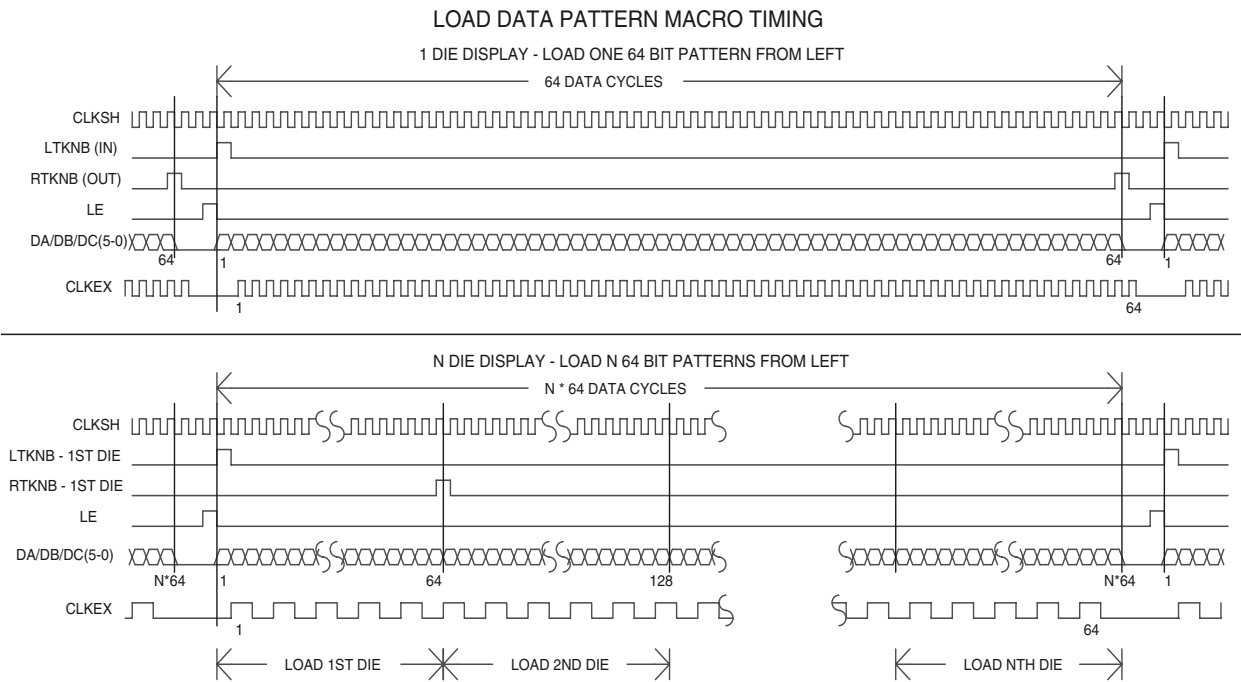
MXED101 DIE PINOUT
NOT TO SCALE

MXED101 Product Description

Pad	Name	Pad Location (in microns)	Pad	Name	Pad Location (in microns)
1	ISHRT	18392,338	36	DC(3)	11272,2352
2	ISHRT	18392,511	37	DC(2)	11042,2352
3	TEST(2)	18392,693	38	DC(1)	10814,2352
4	V _{DD}	18392,854	39	DC(0)	10584,2352
5	V _{DD}	18392,1027	40	DB(5)	7781,2352
6	V _{DD}	18392,1201	41	DB(4)	7552,2352
7	TST(0)	18392,1383	42	DB(3)	7322,2352
8	GND	18392,1543	43	DB(2)	7093,2352
9	RTKNB	18392,1805	44	DB(1)	6864,2352
10	TST(1)	17997,2352	45	DB(0)	6635,2352
11	TST(2)	17823,2352	46	DA(5)	6406,2352
12	TST(3)	17650,2352	47	DA(4)	6232,2352
13	TST(4)	17476,2352	48	DA(3)	6058,2352
14	TST(5)	17302,2352	49	DA(2)	5885,2352
15	TST(6)	15086,2352	50	DA(1)	5711,2352
16	TST(7)	14910,2352	51	DA(0)	5538,2352
17	GND	14736,2352	52	STBY	1920,2352
18	DIRTKN	14542,2352	53	TST(8)	1747,2352
19	GA(1)	14368,2352	54	TST(9)	1573,2352
20	GB(1)	14195,2352	55	LE	1400,2352
21	GC(1)	14021,2352	56	CLKEX	1226,2352
22	SDM(1)	13848,2352	57	CLKSH	1052,2352
23	SDM(0)	13674,2352	58	GND	209,2352
24	RSTB	13500,2352	59	V _{CC}	35,2352
25	V _{CC}	13327,2352	60	LTKNB	0,1739
26	SWC	13153,2352	61	GND	0,1543
27	TGR	12980,2352	62	GG	0,1383
28	GA(2)	12806,2352	63	RG	0,1214
29	GA(0)	12632,2352	64	V _{DD}	0,1032
30	GB(2)	12459,2352	65	V _{DD}	0,858
31	GB(0)	12285,2352	66	V _{DD}	0,685
32	GC(2)	12112,2352	67	TEST(0)	0,524
33	GC(0)	11938,2352	68	TEST(1)	0,356
34	DC(5)	11730,2352	69	ISHRT	0,182
35	DC(4)	11501,2352	70	ISHRT	0,0
71-262	Q(1-192)	427 + 92*(N-1), 129 where N =1 to 192			

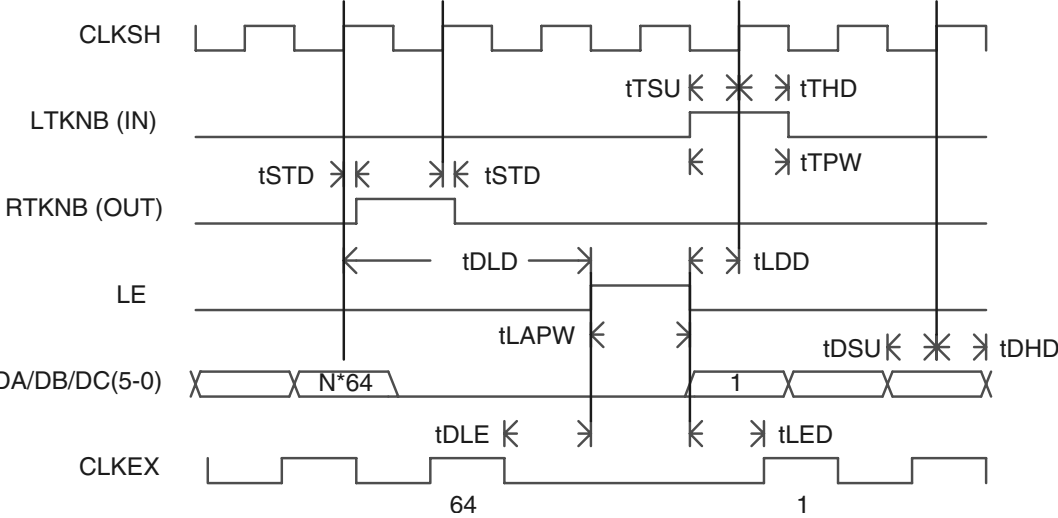
Note: Pad location reference is to bottom left-hand corner.

Timing Diagrams - Load Data Pattern Timing

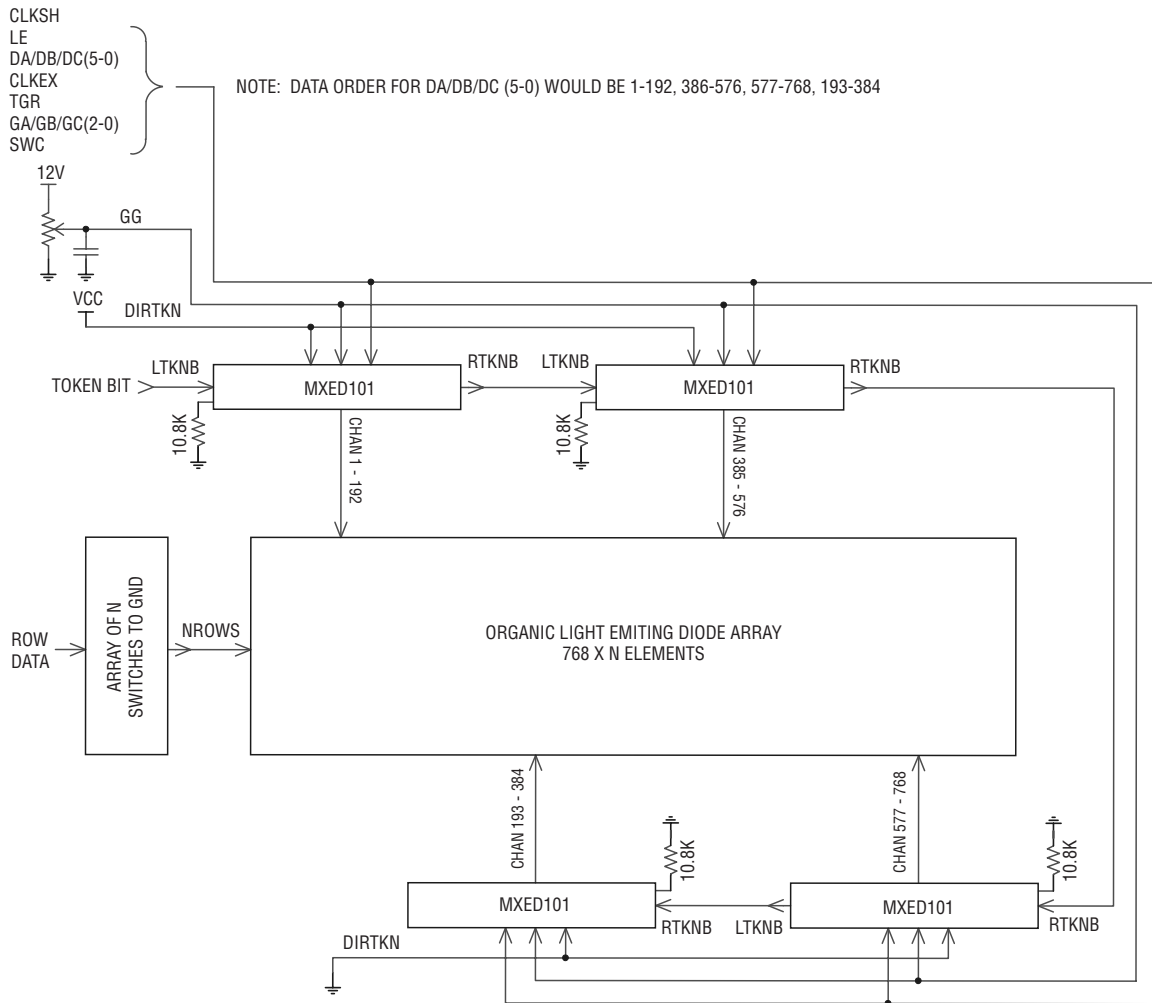


LOAD DATA PATTERN TIMING

LOADING DATA FROM LEFT



Application note:





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MXED101

Notes:

Notes:



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